Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!


## Contact us

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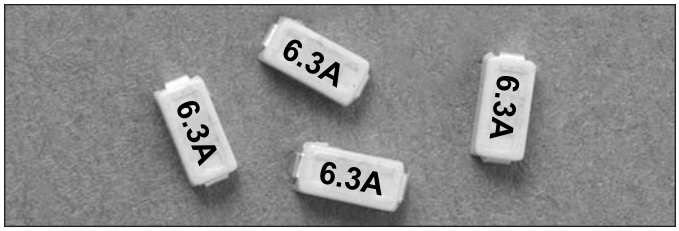
# Time-Delay Chip™ Fuses
## 3216TD Series




### Description
- Time-delay, surface mount fuse
- RoHS compliant, lead-free and halogen-free
- High inrush withstand capability
- Wire-in-Air performance
- Compatible with leaded and lead-free reflow and wave solder

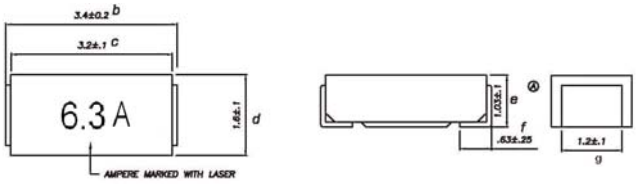
### Agency Information
- c UL us Recognition File number: E19180

### Environmental Data
- Operating temperture range: -55°C to 125°C with proper derating
- Vibration: MIL-STD-202, Method 204 Condition D
- Solderability: ANSI/J-STD-002C, Test B

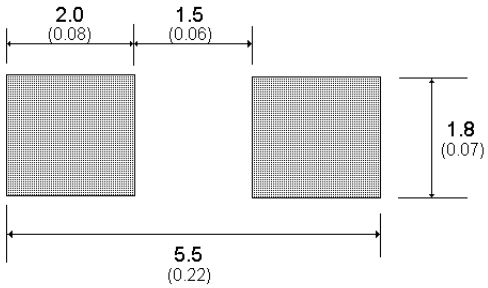
### Ordering
- Specify packaging and product code (i.e., TR/3216TD1-R)

### Soldering Method
- Wave immersion: 260°C, 10 Sec. max.
- Infrared reflow: 260°C, 30 Sec. max.
- Hand solder: 350°C, 3 Sec. max.

### Dimensions - mm (in)
Drawing Not to Scale




### Recommended Pad Layout - mm (in)



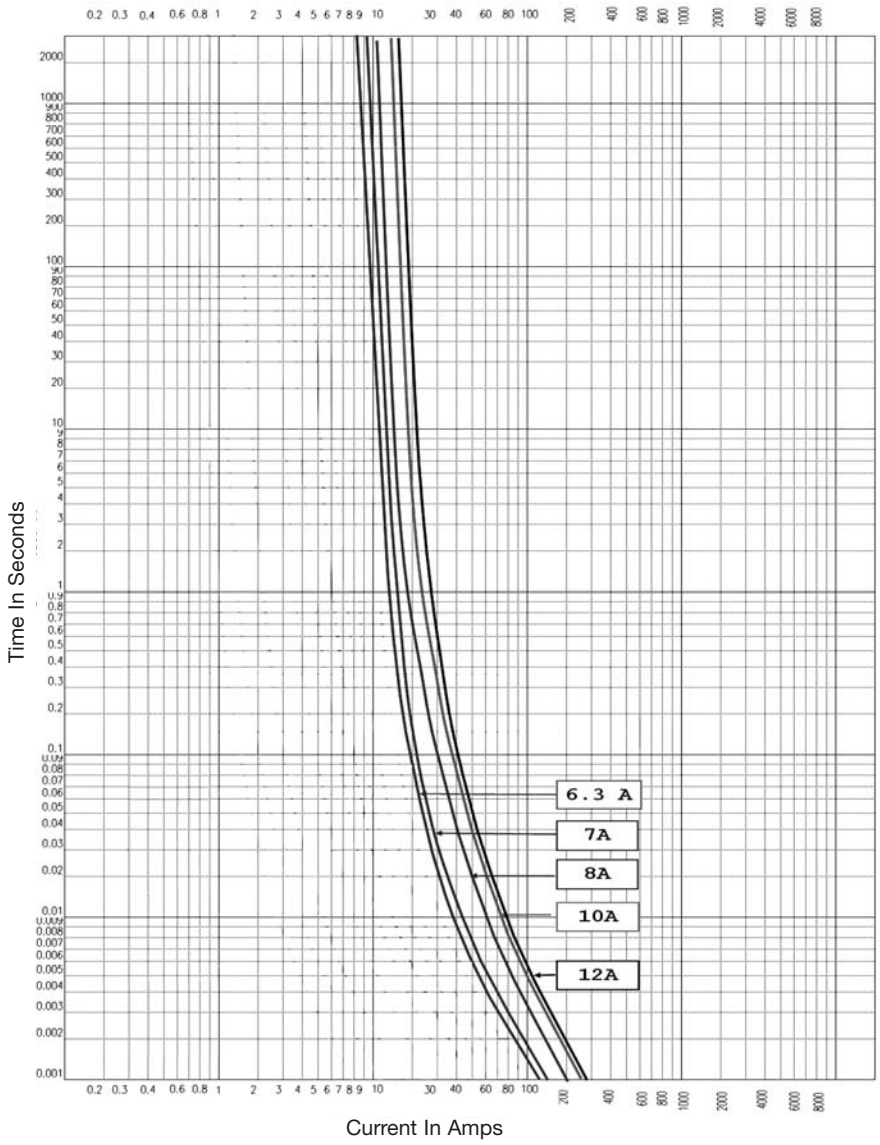

| Electrical Characteristics | |
|---|---|
| **% of Amp Rating** | **Opening Time** |
| 100% | 4 Hours Minimum |
| 200% | 1 Sec. Minimum, 120 Sec. Maximum |
| 300% | 0.05 Sec. Minimum, 3 Sec. Maximum |
| 800% | 0.002 Sec. Minimum, 0.05 Sec. Maximum |

**Specifications**

| Product Code | Current Rating Amps | Voltage Rating | | Interrupting Rating (Amps)* | | Typical Resistance (Ω)** | Typical Melt I²t† DC | Typical Voltage Drop (mV)‡ |
|---|---|---|---|---|---|---|---|---|
| | | Vac | Vdc | AC | DC | | | |
| 3216TD6.3-R | 6.3 | 32 | 32 | 35 | 35 | 0.006 | 10.54 | 56 |
| 3216TD7-R | 7 | 32 | 32 | 35 | 35 | 0.006 | 12.03 | 64 |
| 3216TD8-R | 8 | 32 | 32 | 35 | 35 | 0.0055 | 16.03 | 65 |
| 3216TD10-R | 10 | 32 | 32 | 35 | 35 | 0.0045 | 42.71 | 72 |
| 3216TD12-R | 12 | 32 | 32 | 35 | 35 | 0.00425 | 45.56 | 79 |

* AC Interrupting Rating (Measured at rated voltage with a unity power factor); DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
** DC Cold Resistance (Measured at 10% of rated current)
† Typical Melting I²t (Measured with a battery bank at rated DC voltage, 10x-rated current at 1 microsecond, not to exceed IR. Above 7A uses 70 micron thickness copper layer test board of IEC 60127-3. Others uses 35 micron thickness copper layer.
‡ Typical Voltage Drop (Measured at rated current after temperature stabilizes)
Device designed to carry rated current for four hours minimum. An operating current of 80% or less of rated current is recommended, with further derating required at elevated ambient temperatures.

## Time-Current Curves




| Packaging | |
|---|---|
| **Packaging Code Prefix** | **Description** |
| **TR** | 2500 fuses on 12mm tape-and-reel on a 180mm reel per EIA-481-A & IEC286-3 |



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